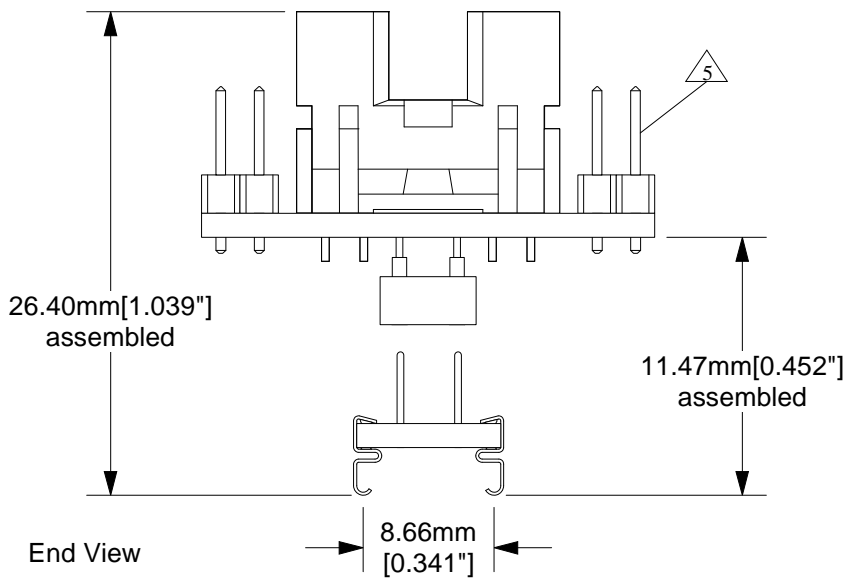
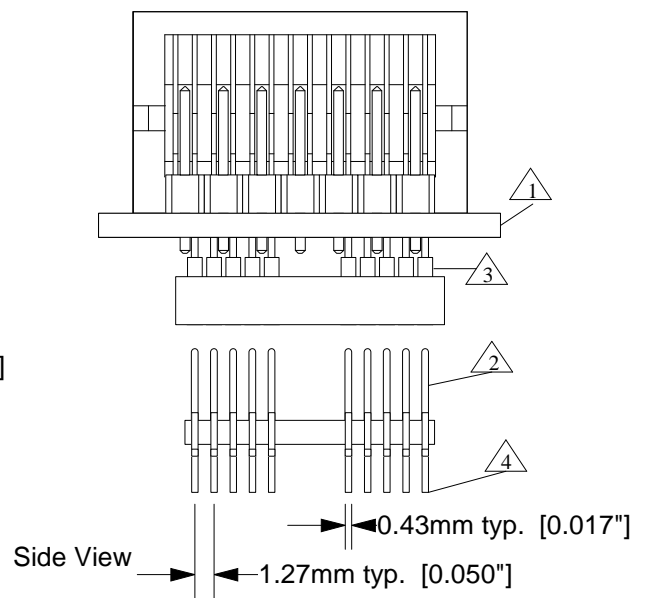


Top View



End View



Side View

△1 Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"]  
FR4/G10 or equivalent high temp material. 17µm [1/2 oz.] Cu clad. SnPb plating.

△2 Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).

△3 Pins: shell material- Brass Alloy 360 1/2 hard; finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.). Contact material- BeCu; finish 0.25µm [10µ"] Au over 2.54µm [100µ"] Ni (min. ).


△4 Leads: material- BeCu Alloy 194; plating- 60/40 SnPb 3.80-10.16µm [150-400µ"].

△5 Test points: material- Phosphor Bronze; plating- Sn over 1.27µm [50µ"] Ni. Gold flash on contact end.

**Description: CARRIER ADAPTOR:**

SOP ZIF socket with test points to 20 position TSOP surface-mountable foot. Mini Grid Array (MGA) interface provides plugability between two halves.

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise.

<b>CA-SO20D-Z-J-T-01 Drawing</b>		Status: Released	Scale: 2:1	Rev: F
 <p>© 1994 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com</p>	Drawing: P. Jasmin		Date: 3/25/94	
	File: CA-SO20D-Z-J-T-01		Modified: 5/15/00	